Material Composition Specification

SOT-543 Case

Device average mass . . . . **2.60 mg**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	6.15%	0.16	Si	7440-21-3	6.15%	0.16	61,515
bond wire	gold or copper	1.54%	0.04	Au	7440-57-5	1.54%	0.04	15,379
				Cu	7440-50-8			
leadframe	Alloy 42	17.30%	0.45	Fe	7439-89-6	10%	0.26	99,962
				Ni	7440-02-0	7.3%	0.19	73,049
encapsulation	EMC GREEN	74.97%	1.95	silica	60676-86-0	57.67%	1.5	576,701
				epoxy resin	37382079-9	7.5%	0.195	74,971
				phenol resin	9003-35-4	7.5%	0.195	74,971
				carbon black	1333-86-4	0.19%	0.005	1,922
				metal hydroxide	1309-42-8	2.11%	0.055	21,146
plating	matte tin	0.04%	0.001	Sn	7440-31-5	0.04%	0.001	384

R0 (18-December 2012)